



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-09-13
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KKK7*D350CC6	A	SH1A	2018-09-13
	Amount	UoM	Unit type	ST ECOPACK Grade
	130	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	8.6x3.9x1.52	14	gull wing	
Comment	K7 SO 14 .15 TO JEDEC MS-012; MDF valid for TD350ETR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
;				
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	KKK7*D350CC6				5000001.0	1000008.0	
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	M-011 Other inorganic materials	3.775	mg	supplier	die	Silicon (Si)	7440-21-3		3.619	mg	958675	27838	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.037	mg	9801	285	
				supplier	metallization	Copper (Cu)	7440-50-8		0.001	mg	265	8	
				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	1060	31	
				supplier	Passivation	Silicon Nitride	12033-89-5		0.011	mg	2914	85	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.063	mg	16689	485	
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.040	mg	10596	308	
Leadframe	M-004 Copper and its alloys	34.926	mg	supplier	alloy	Copper (Cu)	7440-50-8		33.885	mg	970194	260654	
				supplier	alloy	Iron (Fe)	7439-89-6		0.797	mg	22820	6131	
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.048	mg	1374	369	
				supplier	alloy	Zinc (Zn)	7440-66-6		0.042	mg	1203	323	
				supplier	metallization	Nickel (Ni)	7440-02-0		0.139	mg	3980	1069	
	M-008 Precious metals	supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	143	38			
	M-008 Precious metals	supplier	metallization	Gold (Au)	7440-57-5		0.007	mg	200	54			
	supplier	metallization	Silver (Ag)	7440-22-4		0.003	mg	86	23				
	Die attach	M-015 Other organic materials	1.292	mg	supplier	glue	Silver (Ag)	7440-22-4		1.134	mg	877709	8723
					supplier	glue	Isobornyl Methacrylate	7534-94-3		0.065	mg	50310	500
supplier					glue	Acrylate resin	5888-33-5		0.065	mg	50310	500	
supplier					glue	Methyl acrylate polymer	87320-05-6		0.026	mg	20124	200	
supplier					glue	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3		0.001	mg	774	8	
supplier					glue	Tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	774	8	
supplier					wire	Copper (Cu)	7440-50-8		0.094	mg	1000000	723	
Bonding wires	M-011 Other inorganic materials	0.094	mg	supplier	wire	Copper (Cu)	7440-50-8		0.094	mg	1000000	723	
				supplier	mold compound	Silica, vitreous	60676-86-0		78.854	mg	876994	606569	
				supplier	mold compound	Epoxy resin	85954-11-6		3.597	mg	40005	27669	
				supplier	mold compound	Epoxy	29690-82-2		3.597	mg	40005	27669	
				supplier	mold compound	phenol resin	Proprietary		2.697	mg	29995	20746	
Encapsulation	M-011 Other inorganic materials	89.914	mg	supplier	mold compound	additive	Proprietary		0.899	mg	9998	6915	
				supplier	mold compound	carbon black	1333-86-4		0.270	mg	3003	2077	